

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

1-11. *(Canceled)*

12. *(Currently Amended)* A lithography system configured to reduce wafer slipping, comprising:

[[a]] a wafer chuck configured to receive a wafer; and

[[b]] ~~an expander comprising~~ an expandable annular tube coupled to the wafer chuck and configured to expand the wafer chuck without substantially expanding the wafer, such that an initial stress at an interface between the wafer and the wafer chuck is created.

13. *(Canceled)*

14. *(Previously Presented)* The system of claim 12, wherein said annular tube is coupled to an outer edge of said wafer chuck.

15. *(Withdrawn)* The system of claim 13, wherein said annular ring fits within a cavity in said wafer chuck.

16. - 22. *(Canceled)*

23. *(Currently Amended)* The system of claim 12, wherein said ~~expander~~ annular tube is configured to expand said wafer chuck in a uniform manner.
24. *(New)* The system of claim 12, wherein said annular tube comprises a metal.
25. *(New)* The system of claim 12, wherein said annular tube comprises a plastic.
26. *(New)* The system of claim 12, wherein said annular tube includes a cavity, and wherein the cavity is configured to be filled with one of a gas and a liquid.
27. *(New)* The system of claim 12, further comprising:
a temperature sensor coupled to the wafer chuck.
28. *(New)* The system of claim 12, wherein said wafer chuck is configured to releasably secure or hold the wafer by vacuum clamping.
29. *(New)* The system of claim 12, wherein said wafer chuck is configured to releasably secure or hold the wafer by electrostatic clamping.